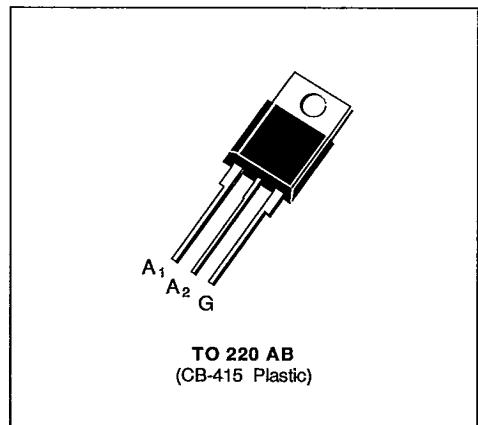


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**SNUBBERLESS TRIACS**

- $I_{TRMS} = 10 \text{ A}$  at  $T_c = 100^\circ\text{C}$ .
- $V_{DRM} : 200 \text{ V}$  to  $800 \text{ V}$ .
- $I_{GT} = 75 \text{ mA}$  (QI-II-III).
- GLASS PASSIVATED CHIP.
- HIGH SURGE CURRENT :  $I_{TSM} = 100 \text{ A}$ .
- HIGH COMMUTATION CAPABILITY :  
 $(di/dt)_c > 12 \text{ A/ms}$  without snubber.

**DESCRIPTION**

New range suited for applications such as phase control and static switching on inductive or resistive load.

**ABSOLUTE RATINGS** (limiting values)

Symbol	Parameter	Value	Unit
$I_{TRMS}$	RMS on-state current (360 ° conduction angle)	10	A
$I_{TSM}$	Non repetitive surge peak on-state current ( $T_j$ initial = $25^\circ\text{C}$ )	$t = 8.3 \text{ ms}$	105
		$t = 10 \text{ ms}$	100
$I^2t$	$I^2t$ value	$t = 10 \text{ ms}$	$\text{A}^2\text{s}$
$di/dt$	Critical rate of rise of on-state current (1)	Repetitive $F = 50 \text{ Hz}$	20
		Non Repetitive	100
$T_{stg}$ $T_j$	Storage and operating junction temperature range	-40, +150 -40, +125	$^\circ\text{C}$

Symbol	Parameter	BTB 10-					Unit
		200 AW	400 AW	600 AW	700 AW	800 AW	
$V_{DRM}$	Repetitive peak off-state voltage (2)	$\pm 200$	$\pm 400$	$\pm 600$	$\pm 700$	$\pm 800$	V

(1) Gate supply :  $I_G = 750 \text{ mA}$  -  $di_G/dt = 1 \text{ A}/\mu\text{s}$ .(2)  $T_j = 125^\circ\text{C}$ .

## THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
R <sub>th</sub> (J - a) <sub>DC</sub>	Junction to ambient	60	°C/W
R <sub>th</sub> (J - c) <sub>DC</sub>	Junction to case for DC	2.7	°C/W
R <sub>th</sub> (J - c) <sub>AC</sub>	Junction to case for 360° conduction angle (F = 50 Hz)	2	°C/W

## GATE CHARACTERISTICS (maximum values)

P<sub>GM</sub> = 40 W (t = 10 µs) P<sub>G (AV)</sub> = 1 W I<sub>GM</sub> = 4 A (t = 10 µs) V<sub>GM</sub> = 16 V (t = 10 µs).

## ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions			Quadrants	Min.	Typ.	Max.	Unit
I <sub>GT</sub>	T <sub>j</sub> = 25 °C	V <sub>D</sub> = 12 V	R <sub>L</sub> = 33 Ω	I-II-III	2		75	mA
V <sub>GT</sub>	T <sub>j</sub> = 25 °C	V <sub>D</sub> = 12 V	R <sub>L</sub> = 33 Ω	I-II-III			1.5	V
V <sub>GD</sub>	T <sub>j</sub> = 125 °C	V <sub>D</sub> = V <sub>DRM</sub>	R <sub>L</sub> = 3.3 kΩ	I-II-III	0.2			V
I <sub>H*</sub>	T <sub>j</sub> = 25 °C Gate open	I <sub>T</sub> = 100 mA R <sub>L</sub> = 140 Ω					75	mA
I <sub>L</sub>	T <sub>j</sub> = 25 °C	V <sub>D</sub> = 12 V	I <sub>G</sub> = 500 mA	I-III	75			mA
		Pulse duration > 20 µs		II	150			
V <sub>TM</sub> *	T <sub>j</sub> = 25 °C	I <sub>TM</sub> = 14 A	t <sub>p</sub> = 10 ms				1.65	V
I <sub>DRM*</sub>	T <sub>j</sub> = 25 °C T <sub>j</sub> = 125 °C	V <sub>DRM</sub> rated	Gate open				0.01 2	mA
dV/dt*	T <sub>j</sub> = 125 °C Linear slope up to 0.67 V <sub>DRM</sub>	Gate open			750	1000		V/µs
(dI/dt) <sub>c</sub> *	T <sub>j</sub> = 125 °C Without snubber	V <sub>DRM</sub> rated			12	24		A/ms
t <sub>gt</sub>	T <sub>j</sub> = 25 °C I <sub>T</sub> = 14 A	dI <sub>G</sub> /dt = 3.5 A/µs V <sub>D</sub> = V <sub>DRM</sub>	I <sub>G</sub> = 500 mA	I-II-III		2		µs

\* For either polarity of electrode A<sub>2</sub> voltage with reference to electrode A<sub>1</sub>.

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T-25-15

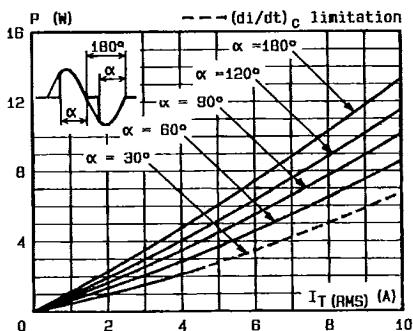
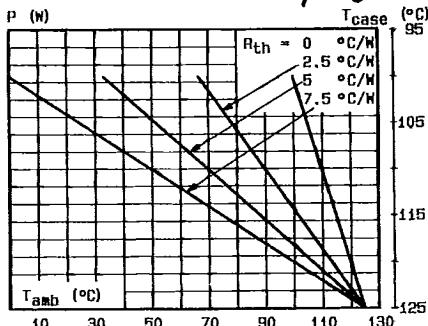
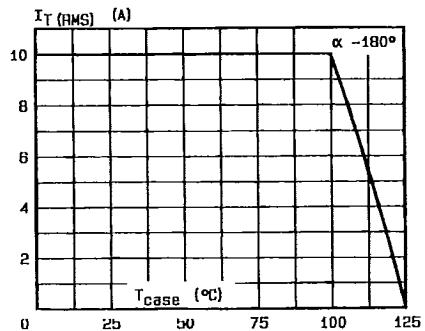
Fig.1 - Maximum mean power dissipation versus RMS on-state current ( $f = 60$  Hz).Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures ( $T_{amb}$  and  $T_{case}$ ) for different thermal resistances heatsink + contact.

Fig.3 - RMS on-state current versus case temperature.

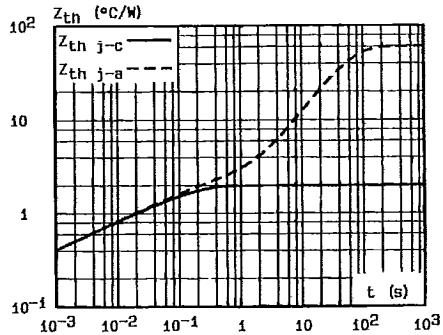


Fig.4 - Thermal transient impedance junction to case and junction to ambient versus pulse duration.

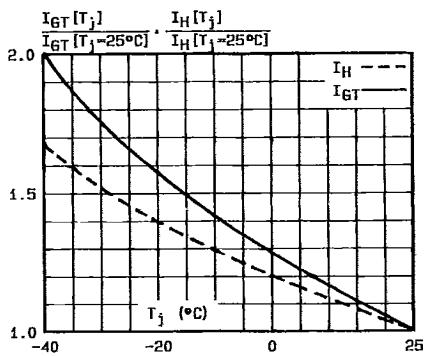


Fig.5 - Relative variation of gate trigger current and holding current versus junction temperature.

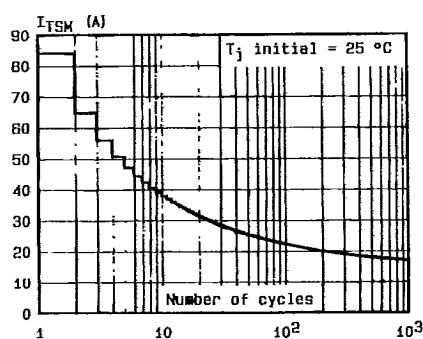


Fig.6 - Non repetitive surge peak on-state current versus number of cycles.

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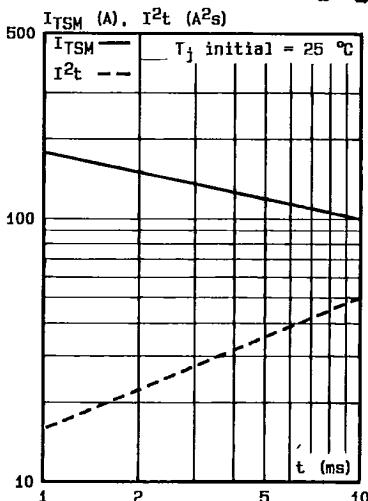


Fig.7 - Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t \leq 10$  ms, and corresponding value of  $I^2t$ .

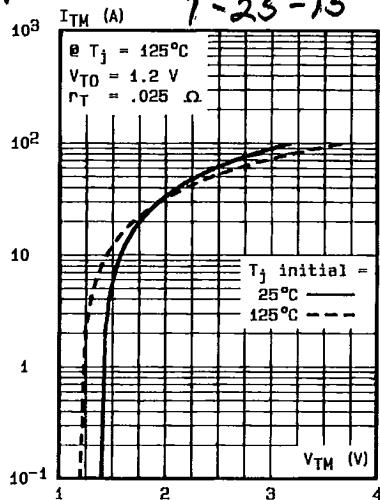
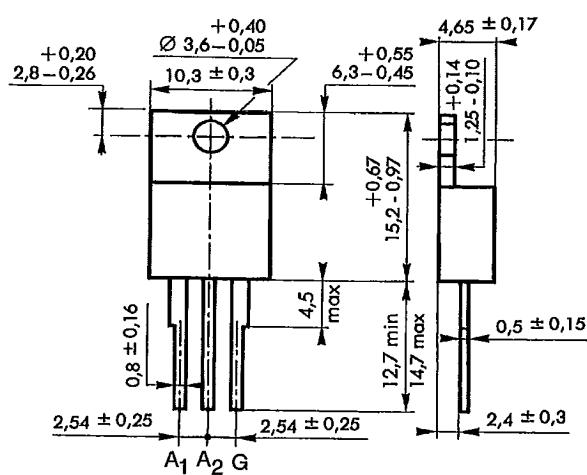


Fig.8 - On-state characteristics (maximum values).

## PACKAGE MECHANICAL DATA

TO 220 AB (CB-415) Plastic



Cooling method : by conduction (method C)

Marking : type number

Weight : 2 g